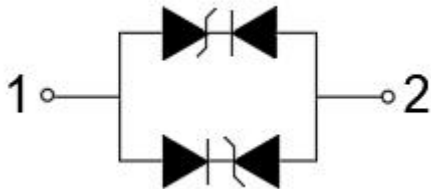


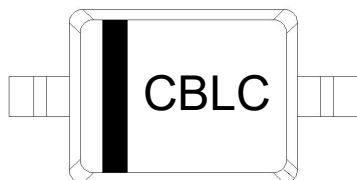
## Features

- 2-pin lead-less package
- Low Junction capacitance (Max value: 1.5pF)
- Peak Pulse current (8/20  $\mu$ s) MAX : 7A
- IEC61000-4-2 (ESD)  $\pm$ 30kV (air),  $\pm$ 30kV (contact)
- Low leakage current
- Working voltages:24V
- RoHS Compliant

## Appearance & Symbol



## Marking Information



CBLC=Marking Code

## Mechanical Characteristics

- Package: SOD-323
- Lead Finish:Matte Tin
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Tape Reel :3000pcs

## Applications

- LED Lighting Modules
- RS232/RS485
- CAN and LIN Bus
- Portable Instrumentation
- General Purpose I/O
- Automotive application

**Absolute Maximum Ratings** (T=25°C, RH=45%-75%, unless otherwi

Parameters	Symbol	Value	Unit
Peak Pulse Power (tp=8/20µs waveform)	P <sub>PP</sub>	315	W
Peak Pulse Current (8/20µs)	I <sub>PP</sub>	7	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	±30 ±30	KV
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

**Electrical Characteristics** (T=25°C, RH=45%-75%, unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V <sub>RWM</sub>				24	V
Reverse Breakdown Voltage	V <sub>(BR)R</sub>	I <sub>R</sub> = 1mA	26.7		31	V
Reverse Leakage Current	I <sub>R</sub>	V <sub>R</sub> = 24V			1	uA
Clamping voltage	V <sub>C</sub>	I <sub>PP</sub> = 1A, T <sub>P</sub> =8/20us			35	V
Clamping voltage	V <sub>C</sub>	I <sub>PP</sub> = 7A, T <sub>P</sub> =8/20us			45	V
Junction capacitance	C <sub>j</sub>	V <sub>R</sub> = 0V, f = 1MHz		1	1.5	pF

Typical Characteristics

FIG1: Power rating derating curve

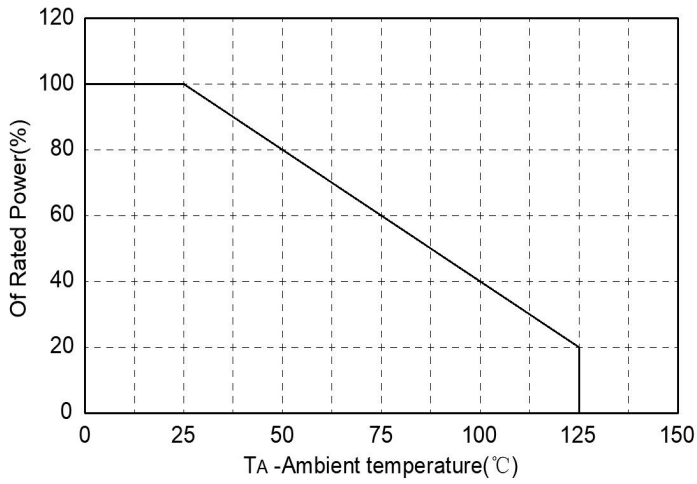


FIG2: pulse Waveform

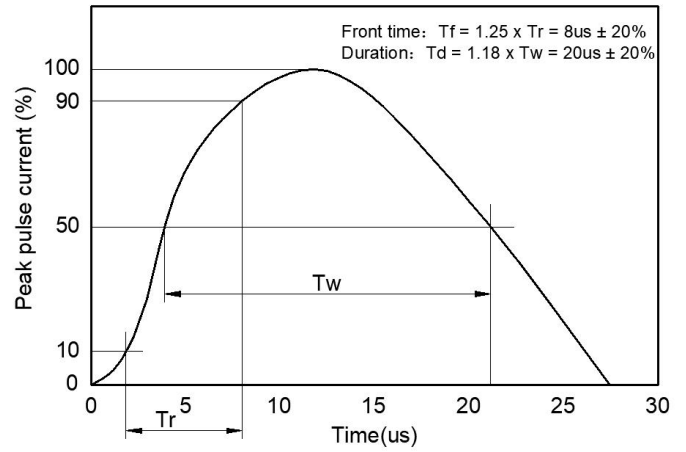


FIG3: Capacitance between terminals characteristics

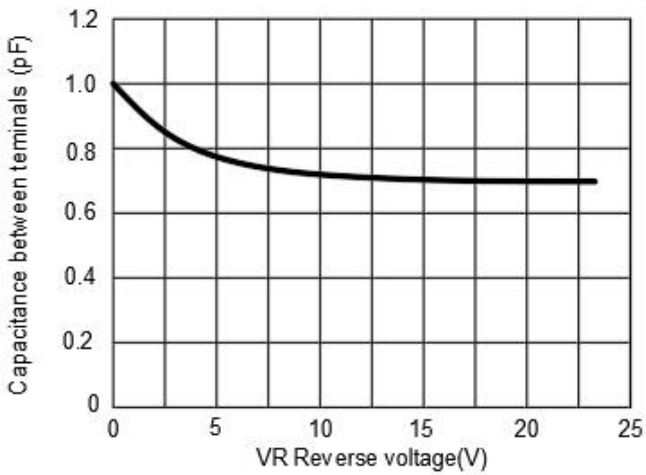
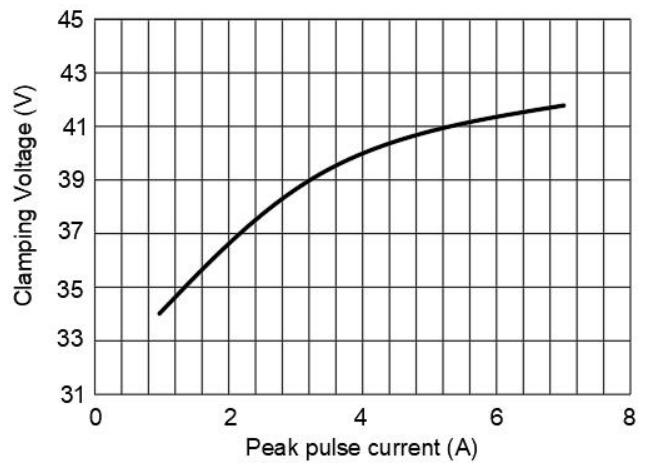
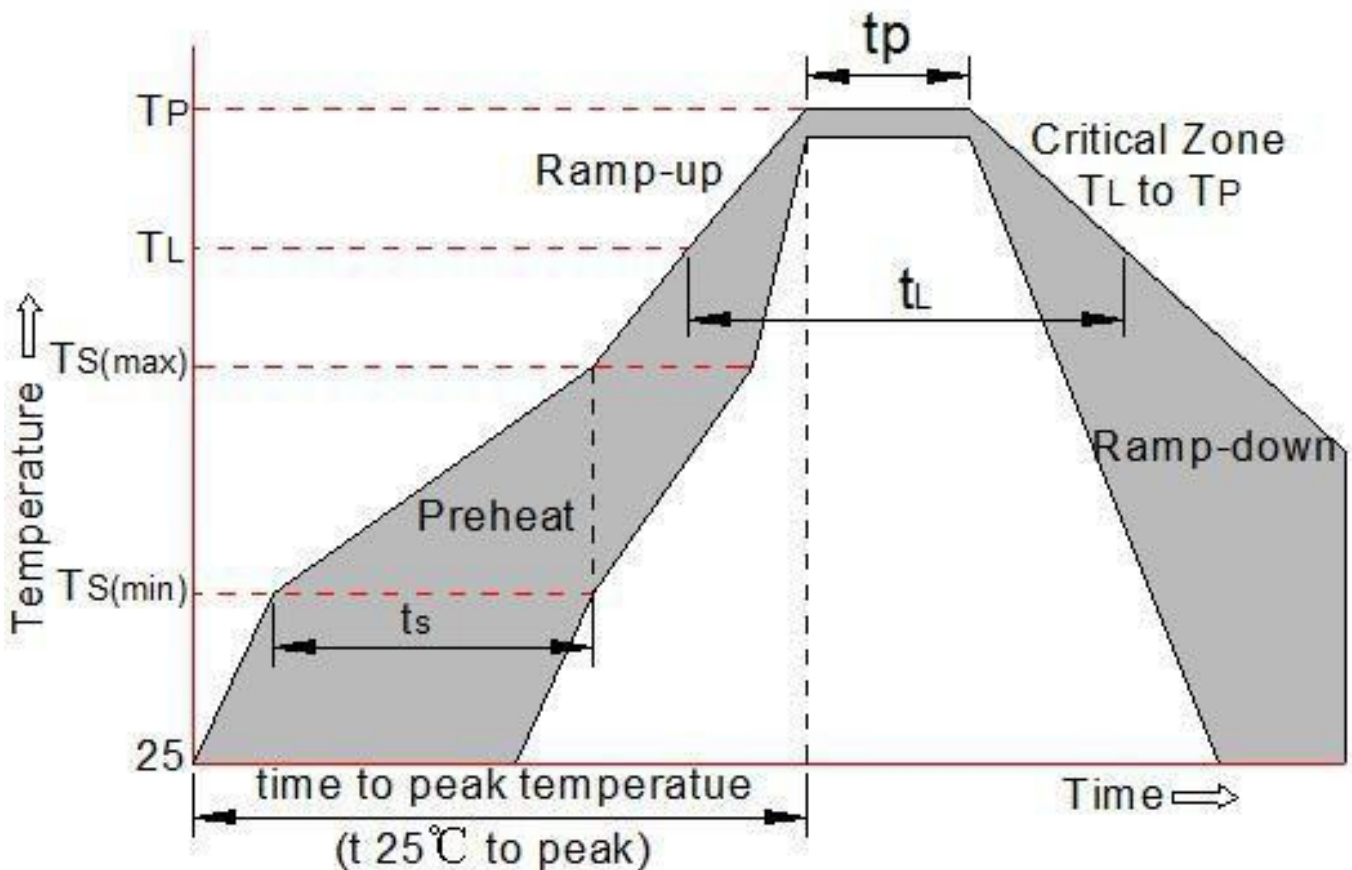


FIG4: Clamping Voltage vs. Peak Pulse Current

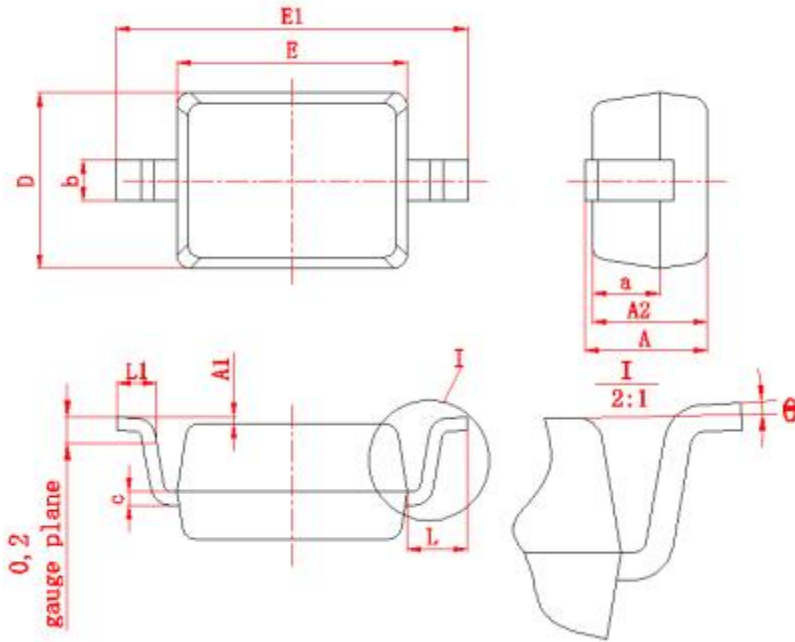


Soldering parameters

Reflow Condition		Pb-Free assembly see as bellow
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ ) (Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260°C

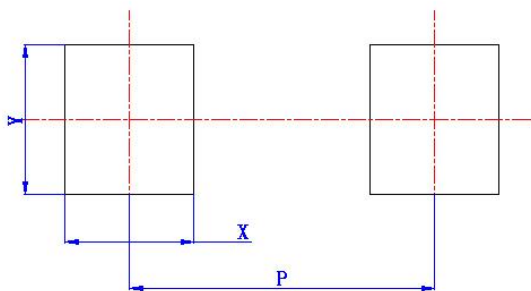


Package mechanical data



Symbol	Dimension in Millimeters	
	min	max
A	0.80	1.05
A1	0	0.1
A2	0.8	0.95
a	(0.5)	
D	1.2	1.4
E	1.6	1.8
E1	2.5	2.75
b	0.25	0.35
c	0.08	0.15
L	(0.475)	
L1	0.25	0.45
θ	0°	8°

Suggested Land Pattern



Symbol	Dimension in Millimeters
	typ
X	(0.7)
Y	(0.7)
P	(2.3)